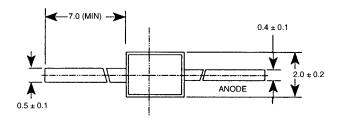


SURFACE MOUNT LED LAMP FLAT TYPE

RED QTLP282-2 CLEAR YELLOW QTLP282-3 CLEAR GREEN QTLP282-4 CLEAR AIGaAs/RED QTLP282-7 CLEAR

PACKAGE DIMENSIONS



0.16 ± 0.05 1.1 2.5 ± 0.2 0.8 ± 0.1 1.3 ± 0.2

DESCRIPTION

These subminiature LED lamps are intended for high volume, low cost status indication on PCBs, and for backlighting keyboards and switches. They are compatible with vapor phase reflow or wave solder surface mount equipment. Available in "Gull-Wing" lead bend configuration. They have clear, flat lenses. Tape and reel options are also available.

FEATURE

- Subminiature package
- Flat package profile
- Wide viewing angle
- Lead bend options for surface mounting

ST1709

NOTES:

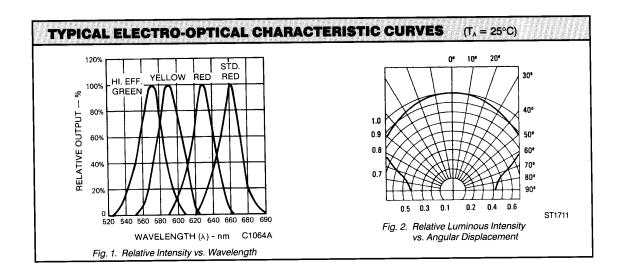
- 1. ALL DIMENSIONS ARE IN MILLIMETERS
- 2. LEAD SPACING IS MEASURED WHERE THE LEADS EMERGE FROM THE PACKAGE
- 3. PROTRUDED RESIN UNDER THE FLANGE IS 1.5 mm (0.059") MAXIMUM

ABSOLUTE MAXIMUM RATINGS (TA	25°C unless ot	herwise specified		
PART NUMBER QTLP-	282-2	282-3	282-4	282-7
DC forward current (I _i) Operating temperature range Storage temperature range Lead soldering time (at 1/16 inch (1.6 mm) from the bottom of lamp)	30 mA	20 mA -40°C to - -40°C to + 5 seconds @	-100°C	40 mA
Peak forward current (at f=1.0 KHz, Duty factor=1/10)	160 mA	160 mA	160 mA	200 mA
Power dissipation (P _d)	100 mW	85 mW 20 m	100 mW A	110 mA



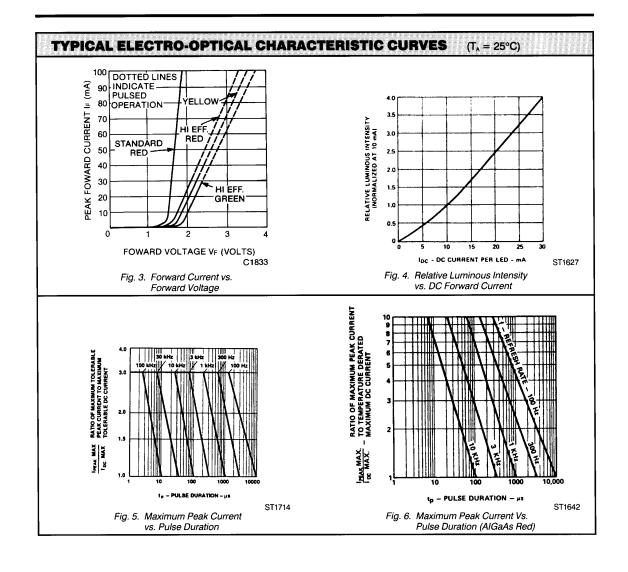
SURFACE MOUNT LED LAMP FLAT TYPE

PART NUMBER	282-2	282-3	282-4	282-7	TEST CONDITIONS
Luminous intensity (mcd)					I _F =20 mA
minimum	1.5	3.5	1.0	11	
typical	5.6	6.0	5.6	17	
Forward voltage (V _F)					$I_F=20 \text{ mA}$
minimum	1.7	1.7	1.7	1.7	
typical	2.0	2.0	2.1	2.0	
maximum	2.8	2.8	2.8	2.8	
Peak wavelength (nm)	640	585	565	660	I₅=20 mA
Spectral line half width (nm)	45	35	30	20	$I_F=20 \text{ mA}$
Reverse breakdown voltage (V _R)	5	5	5	5	$I_R = 10 \mu A$
Viewing angle (°)	150	150	150	150	$I_F=20 \text{ mA}$





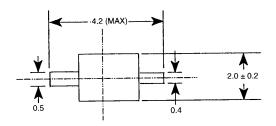
SURFACE MOUNT LED LAMP FLAT TYPE





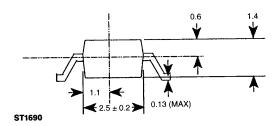
SURFACE MOUNT OPTION FOR QTLP282-X FLAT TYPE LED LAMP GULL WING LEAD CONFIGURATION

LEAD BEND OPTIONS



DESCRIPTION

These flat package LED lamps are encapsulated in an axial lead package with a clear lens. Automatic placement equipment can be used to mouont these LEDs on PC boards. The lamps can be mounted using either batch or in line vapor phase reflow solder processes. Subminature lamps are availabe in red, high efficiency red, yellow, and green.



FEATURES

- Gull Wing lead configuration for surface mount application
- Compatible with automatic placement equipment
- Compatible with vapor phase reflow solder processes.
- Supplied on tape and reel or in bulk packaging

ABSOLUTE MAX	IMUM RATING (T _A = 25°C Unless Otherwise Specified)
Wave soldering temperature (1.6 mm (0.063") from body) Surface Mount Reflow	
Soldering: Convective IR	

ABSOLUTE MAXIMUM SOLDER RATINGS AND ELECTRICAL/OPTICAL CHARACTERISTICS

The absolute maximum ratings and electrical/optical specifications are identical to the basic catalogue device, except for the vapor phase soldering rating as specified above.



SURFACE MOUNT LED LAMP FLAT TYPE

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